

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0904NSI	**Issued**	23. June 2021
MA#	MA005434191		
Package	PG-TSDSON-8-35	**Weight***	34.46 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.303	0.88	0.88	8808	8808
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		106	
	non noble metal	zinc	7440-66-6	0.015	0.04		425	
	non noble metal	iron	7439-89-6	0.293	0.85		8508	
	non noble metal	copper	7440-50-8	11.903	34.55	35.45	345468	354507
wire	noble metal	gold	7440-57-5	0.030	0.09	0.09	863	863
encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		1039	
	plastics	epoxy resin	-	1.647	4.78		47794	
	inorganic material	silicondioxide	60676-86-0	16.217	47.07	51.95	470669	519502
leadfinish	non noble metal	tin	7440-31-5	0.420	1.22	1.22	12203	12203
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	91	91
solder	noble metal	silver	7440-22-4	0.012	0.03		344	
	non noble metal	tin	7440-31-5	0.024	0.07		689	
	non noble metal	lead	7439-92-1	0.439	1.27	1.37	12739	13772
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.075	0.22		2166	
	non noble metal	copper	7440-50-8	3.030	8.80	9.03	87953	90254
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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